

DN8797SE

3 V Hall IC

One-way magnetic field operation

■ Overview

The DN8797SE is a 3 V operation Hall IC which includes a Hall element, amplifier circuit, Schmidt circuit, stabilized power supply and temperature compensation circuit which are integrated on a single chip with a fine patterning technology. The magnetic input signal is outputted by being converted to high or low. We have improved the conventional circuit to realize a stable operation covering from low to high supply voltage and from low to high temperature.

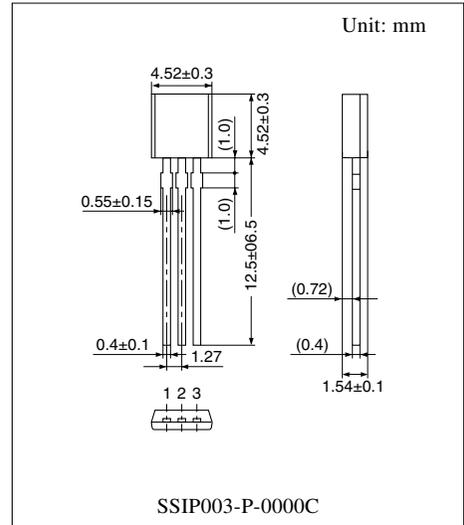
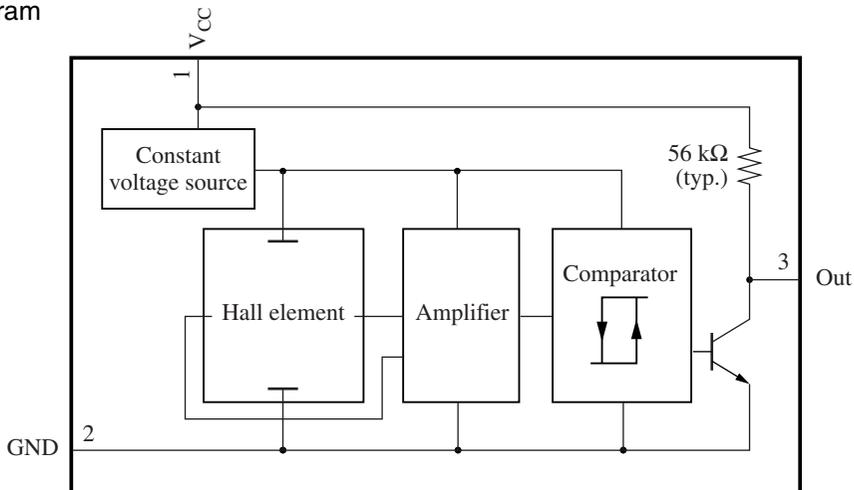
■ Features

- Wide operating supply voltage range
($V_{CC} = 2.7 \text{ V to } 16.0 \text{ V}$)
- Wide operating ambient temperature ($-40^{\circ}\text{C to } +85^{\circ}\text{C}$)
- Package: SIP 3-pins
- Equipped with an output pull-up resistor (typical $56 \text{ k}\Omega$)

■ Applications

- DC brushless motor, fan motor, rotation sensor, detection of cover open/close (example for a cellular phone), position sensor

■ Block Diagram



Note) The package of this product will be changed to lead-free type (SSIP003-P-0000J). See the new package dimensions section later of this datasheet.

■ Pin Descriptions

Pin No.	Symbol	Description
1	V _{CC}	Supply voltage pin
2	GND	Ground pin
3	Out	Output pin

■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	18	V
Output voltage	V _{OUT}	18	V
Supply current	I _{CC}	—	mA
Power dissipation	P _D	250	mW
Operating ambient temperature	T _{opr}	-40 to +100	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) 1. Except for the operating ambient temperature and storage temperature, all ratings are for T_a = 25°C.

2. The reverse insertion of this IC will cause its breakdown.
3. It will operate normally in several tens of ms after power on.
4. This IC is not suitable for car electrical equipment.

■ Recommended Operating Range

Parameter	Symbol	Range	Unit
Supply voltage	V _{CC}	2.7 to 16.0	V

■ Electrical Characteristics at T_a = 25°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Operating magnetic flux density 1	B _{H-L}	V _{CC} = 3 V	—	—	20	mT
Operating magnetic flux density 2	B _{L-H}	V _{CC} = 3 V	3	—	—	mT
Hysteresis width	BW	V _{CC} = 3 V	0.2	1.5	4.0	mT
Output voltage 1	V _{OL1}	V _{CC} = 16.0 V, I _O = 5 mA, B = 20 mT	—	0.07	0.30	V
Output voltage 2	V _{OL2}	V _{CC} = 2.7 V, I _O = 5 mA, B = 20 mT	—	0.07	0.30	V
Output voltage 3	V _{OH1}	V _{CC} = 16.0 V, I _O = -20 μA, B = 3 mT	14.4	14.9	15.4	V
Output voltage 4	V _{OH2}	V _{CC} = 2.7 V, I _O = -20 μA, B = 3 mT	1.05	1.55	2.05	V
Output short-circuit current	-I _{OS}	V _{CC} = 16.0 V, B = 3 mT, V _O = 0 V	0.19	1.27	0.39	mA
Supply current 1	I _{CC1}	V _{CC} = 16.0 V, B = 3 mT	1.0	3.5	6.0	mA
Supply current 2	I _{CC2}	V _{CC} = 2.7 V, B = 3 mT	1.0	2.5	6.0	mA

Note) 1. Symbol B_{H-L} stands for the operating magnetic flux density where its output level varies from high to low.

2. Symbol B_{L-H} stands for the operating magnetic flux density where its output level varies from low to high.

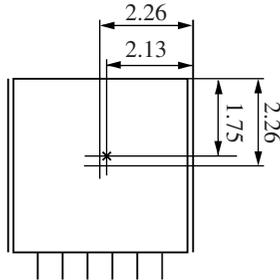
3. The variation of operating magnetic flux density does not depend on supply voltage due to its built-in stabilized power source. (V_{CC} should be confined to the range of 2.7 V to 16.0 V.)

4. A supply current changes by maximum 1 mA when its output level varies from high to low.

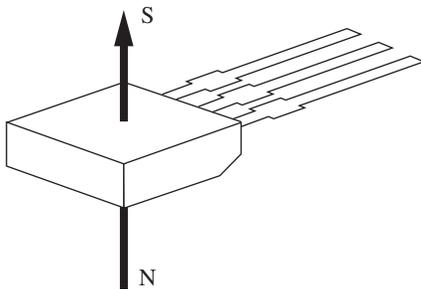
■ Technical Data

- Position of a Hall element (unit in mm)

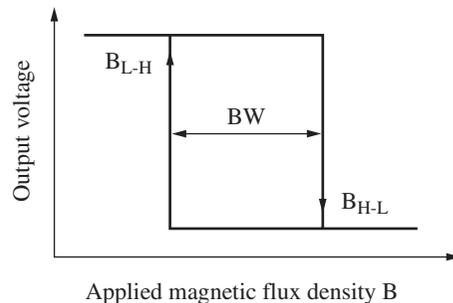
Distance from a package surface to sensor part: 0.42 mm



- Magneto-electro conversion characteristics



Direction of applied magnetic field



■ Caution on Use of Hall ICs

The Hall ICs are often used to detect movement. In such cases, the position of the Hall IC may be changed by exposition to shock or vibration over a long period of time, and it causes the detection level change. To prevent this, fix the package with adhesives or fix it on a dedicated case.

1. A case using an adhesive

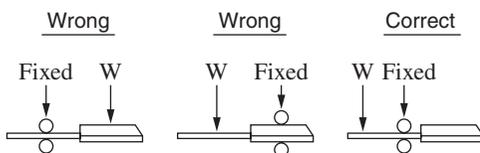
Some kinds of adhesive generate corrosive gas (such as chloric gas) during curing. This corrosive gas corrodes the aluminum on the surface of the Hall IC, and may cause a functional defect of disconnection.

If Hall IC is to be sealed after installation, attention should be given to the adhesive or resin used for peripherals and substrate cleaner, as well as to the adhesive used for Hall IC installation. Please confirm the above matter to those manufacturers before using.

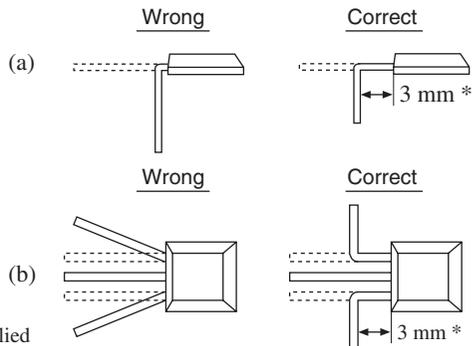
We could not select the specified adhesive, for we find it difficult to guarantee the ingredient of each adhesive.

2. A case bending lead wire

Bend the lead wire without stressing the package.



Bending method of lead wire



Bending position of lead wire

*: The distance can be within 3 mm, if no stress is applied to the resin mold by tightly fixing the lead wires with a metallic mold or the like.

■ Caution on Use of Hall ICs (continued)

3. Power supply line/Power transmission line

If a power supply line/power transmission line becomes longer, noise and/or oscillation may be found on the line. In this case, set the capacitor of 0.1 μF to 10 μF near the Hall IC to prevent it.

If a voltage of 18 V or more is thought to be applied to the power supply line (flyback voltage from coil or the ignition pulse, etc.), avoid it with external components (capacitor, resistor, Zener diode, diode, surge absorbing elements, etc.).

4. V_{CC} and GND

Do not reverse V_{CC} and GND. If the V_{CC} and GND pins are reversely connected, this IC will be destroyed. If the IC GND-pin voltage is set higher than other pin voltage, the IC configuration will become the same as a forward biased diode. Therefore, it will turn on at the diode forward voltage (approximately 0.7 V), and a large current will flow through the IC, ending up in its destruction. (This is common to monolithic IC.)

5. Cautions on power-on of Hall IC

When a Hall IC is turned on, the position of the magnet or looseness may change the output of a Hall IC, and a pulse may be generated. Therefore, care should be given whenever the output state of a Hall IC is critical when the supply power is on.

6. Fixing a Hall IC

When the Hall IC of an insertion type package installed by soldering the lead wire only is to be used under vibration, fix it firmly with a holder. Otherwise, vibration may cause metal fatigue in the lead wire of Hall IC, resulting in wire breakage.

7. On fixing a Hall IC to holder

When a Hall IC is mounted on the printed circuit board with a holder and the coefficient of expansion of the holder is large, the lead wire of the Hall IC will be stretched and it may give a stress to the Hall IC.

If the lead wire is stressed intensely due to the distortion of holder or board, the adhesives between the package and the lead wire may be weakened and cause a minute gap resulting in the deterioration of its resistance to moisture.

Sensitivity may also be changed by this stress.

8. On using flux in soldering

Choose a flux which does not include ingredients from halogen group, such as chlorine, fluorine, etc. The ingredients of halogen group may enter where the lead frame and package resin joint, causing corrosion and the disconnection of the aluminum wiring on the surface of an IC chip.

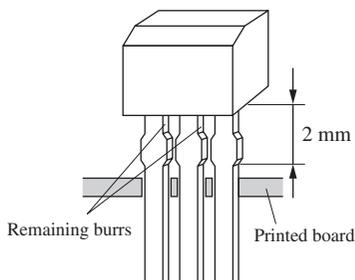
9. In case of the magnetic field of a magnet is too strong

Output may be inverted when applying a magnetic flux density of 100 mT or more. Accordingly, magnetic flux density should be used within the range of 100 mT.

10. On mounting, deburring and soldering of insertion type package

If the leads of a Hall IC in an insertion type package are inserted up to their root part through holes on the printed circuit board, abnormal stress is applied to the package and the reliability of the Hall IC is likely to deteriorate. So, when mounting each Hall IC of the insertion type, insert the leads in due degree at which the bottom face of the package is separated at least 2 mm from the top face of the PCB.

Also note that burrs of epoxy resin may be left sticking to the lead wires. (We are trying to remove such burrs as much as possible in the deburring process, but in some cases, they are not perfectly removable.)



When soldering the leads, remember to separate the soldering position by 2 mm or more from the resin part of the package.

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